


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	WAFER LEVEL MICROELECTRONIC PACKAGING WITH DOUBLE ISOLATION	
Application Type : regular, utility Attorney Docket Number : TESSERA 3.0-395		
Correspondence address: Customer Number: 038091		
		
Inventors Information:		
<u>Inventor 1:</u>		
Applicant Authority Type:	Inventor	
Citizenship:	GB	
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Country of Residence:	US	
Address-1 of Mailing Address:	6226 Paso Los Cerritos	
Address-2 of Mailing Address:		
City of Mailing Address:	San Jose	
State of Mailing Address:	CA	
Postal Code of Mailing Address:	95120	
Country of Mailing Address:	US	
Phone:		
Fax:		
E-mail:		
<u>Inventor 2:</u>		
Applicant Authority Type:	Inventor	
Citizenship:	US	
Given Name:	Bruce	
Family Name:	McWilliams	
Residence:		

City of Residence:	San Jose
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